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## CSP LTST-A07RGB

### **ECN list for datasheet**

Rev.	Effective Date	Description	Issue By
-	2021.08.31	Preliminary	Jeff Hung





# CSP LTST-A07RGB

### 1. Description

CSP LED from Lite-On are available in miniature sizes and special configurations for automated PC board assembly and space-sensitive applications. These CSP LED are suitable for use in a wide variety of electronic equipment, including cordless and cellular phones, notebook computers, network systems, home appliances, and indoor signboard applications.

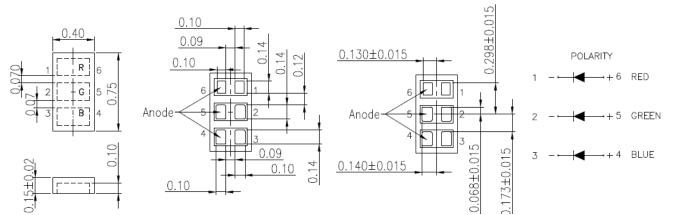
#### **1.1 Features**

- Meet ROHS.
- Extra Thin (0.2Hmm) Full Color CSP LED
- Ultra Bright InGaN / AlInGaP CSP LED.
- Package in 8mm tape on 7" diameter reels.
- EIA STD Package.
- I.C. Compatible.
- Compatible with Automatic Placement Equipment.
- Compatible with Infrared Reflow Solder Process.

#### **1.2 Applications**

- Telecommunication, Office automation, home appliances, industrial equipment
- Keypad/Keyboard Backlighting
- Status indicator
- Micro displays
- Signal and Symbol Luminary

### 2. Package Dimensions



Part No.	Lens Color	Source Color	Pin Assignment
	White Diffused	AllnGaP Red	1,6
LTST-A07RGB		InGaN Green	2,5
		InGaN Blue	3,4

#### Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.05 mm (.004") unless otherwise noted.
- 3. Chip shift  $\pm$  15  $\mu$  m

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### 3. Rating and Characteristics

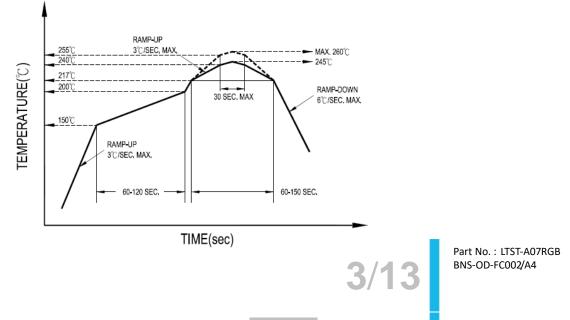
#### 3.1 Absolute Maximum Ratings at Ta=25°C

Parameter	LTST-A07RGB			Unit
	Blue	Red	Green	Onit
Power Dissipation	30	60	30	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	100	80	100	mA
DC Forward Current	10	20	10	mA
Electrostatic Discharge Threshold (HBM)		2000		V
Operating Temperature Range	-30 ℃ to + 80 ℃			
Storage Temperature Range	-30 ℃ to + 100 ℃			
Infrared Soldering Condition	260℃ For 10 Seconds			

Notes :

1. HBM : Human Body Model.

#### 3.2 Suggest IR Reflow Condition For Pb Free Process:





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#### 3.3 Electrical / Optical Characteristics at Ta=25°C

Parameter	Question	Symbol		LTST-A07RGB			Test
Falameter	Symbol		Blue	Red	Green	Unit	Condition
Luminous Intensity	IV	MIN.	20	28	120	mcd	IF : Blue=1.7mA, Red=1.7mA,
	ĨV	MAX.	50	55	240	mod	Green=1.7mA, Note 1
Viewing Angle	<b>2</b> θ <sub>1/2</sub>	TYP.		140		deg	Fig.5
Peak Emission Wavelength	λΡ	TYP.	471	625	534	nm	Measurement @Peak (Fig.1)
	λd	MIN.	464	618	526		IF : Blue=1.7mA,
Dominant Wavelength		TYP.	-	-	-	nm	Red=1.7mA, Green=1.7mA,
		MAX.	474	628	536		Note 3
Spectral Line Half-Width	Δλ	TYP.	25	20	35	nm	
		MIN.	2.1	1.5	2.1		IF : Blue=1.7mA,
Forward Voltage	VF	MAX.	3.1	2.4	3.1	V	Red=1.7mA, Green=1.7mA,
Reverse Current	IR	MAX	10	10	10	μA	VR = 5V Note 5

#### Notes:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the

CIE eye-response curve.

2. Iv classification code is marked on each packing bag.

3. The chromaticity coordinates (x, y) is derived from the 1931 CIE chromaticity diagram.

4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommend to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Reverse voltage (VR) condition is applied to IR test only. The device is not designed for reverse operation

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### 4. Bin Rank

#### 4.1 Bin code list

#### IV Rank

Luminous Inf	tensity Color: Red Unit:	mcd @1.7mA
Bin Code	Min.	Max.
N1	28.0	41.5
N2	41.5	55.0

Tolerance on each Luminous Intensity bin is +/- 10%

Luminous Inte	nsity Color: Green Unit	: mcd @1.7mA
Bin Code	Min.	Max.
R1	120.0	240.0

Tolerance on each Luminous Intensity bin is +/- 10%

Luminous Int	ensity Color: Blue Unit:	mcd @1.7mA
Bin Code	Min.	Max.
L2	20.0	35.0
M1	35.0	50.0

Tolerance on each Luminous Intensity bin is +/- 10%







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#### Hue Rank

Dominant Wa	velength Color: Red Uni	t: nm @1.7mA
Bin Code	Min.	Max.
A	618.0	623.0
В	623.0	628.0

Tolerance for each Dominant Wavelength bin is +/- 1nm

Dominant Wav	elength Color: Green Ur	it: nm @1.7mA
Bin Code	Min.	Max.
С	526.0	531.0
D	531.0	536.0

Tolerance for each Dominant Wavelength bin is +/- 1nm

Dominant Way	velength Color: Blue Uni	t: nm @1.7mA
Bin Code	Min.	Max.
E	464.0	469.0
F	469.0	474.0

Tolerance for each Dominant Wavelength bin is +/- 1nm







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#### 5. Typical Electrical / Optical Characteristics Curves. (25°C Ambient Temperature Unless Otherwise Noted) Blue Red Green 1.0 Relative Intensity 0.5 0.0 71 400 450 500 550 600 650 Wavelength $\lambda$ (nm) Fig. 1 RELATIVE INTENSITY VS. WAVELENGTH 100 40 Blue (m.k) (MA) Red Blue Green 80 Green 30 Forward Current Ip Forward Current Is 60 20 40 Red 10 20 σ 0 2.0 2.8 4.0 0 1.6 2.4 3.6 80 100 3.2 20 40 60 Forward Voltage VF(V) Ambient Temperature TA (°C) Fig. 2 FORWARD CURRENT VS. Fig. 3 FORWARD CURRENT VS. FORWARD VOLTAGE DERATING CURVE 30° 3.0 Relative Luminous Intensity Blue Green 2.5 Normalized at 20mA 40' 2.0 1.0 1.5 Red 50\* 0.9 1.0 60' 0.8 0.5 70° 0.7 0.0 80' 0 40 50 10 20 30 90' Forward Current (mA) 0.6 0.5 0.3 0.1 0.2 0.4 Fig. 4 RELATIVE LUMIOUS INTENSITY VS. FORWARD CURRENT

Fig.5 Spatial Distribution

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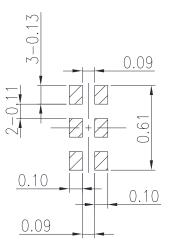
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### 6. User Guide

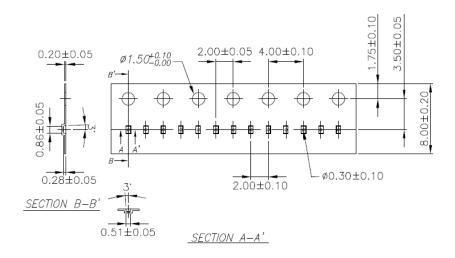
#### 6.1 Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package. If clean is necessary, immerse the LED in ethyl alcohol or in isopropyl alcohol at normal temperature for less one minute.

#### 6.2 Recommend Printed Circuit Board Attachment Pad



#### 6.3 Package Dimensions Of Tape And Reel



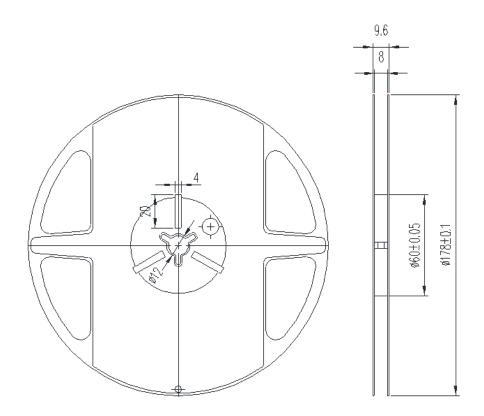
Note:

1. All dimensions are in millimeters (inches).



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#### 6.4 Package Dimensions of Reel



#### Notes:

- i. Empty component pockets sealed with top cover tape.
- ii. 7 inch reel-6000 pieces per reel.
- iii. Minimum packing quantity is 500 pieces for remainders.
- iv. The maximum number of consecutive missing lamps is two.
- v. In accordance with ANSI/EIA 481 specifications.





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### 7. Cautions

#### 7.1 Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications).Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

#### 7.2 Storage

The package is sealed:

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

The storage ambient for the LEDs should not exceed 30°C temperature or 60% relative humidity.

It is recommended that LEDs out of their original packaging are IR-reflowed within one week. (MSL 3).

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant, or in a desiccators with nitrogen ambient.

LEDs stored out of their original packaging for more than one week should be baked at about 60 deg C for at least 20 hours before solder assembly.

#### 7.3 Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

#### 7.4 Soldering

Recommended soldering conditions:

Re	flow soldering	Soldering iron		
Pre-heat	150~200°C	Temperature	300°C Max.	
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.	
Peak temperature	260°C Max.		(one time only)	
Soldering time	10 sec. Max.(Max. two times)			

#### Notes:

Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

LITE-ON Runs both component-level verification using in-house **KYRAMX98** reflow chambers and board-level assembly. The results of this testing are verified through post-reflow reliability testing. Profiles used at LITE-ON are based on JEDEC standards to ensure that all packages can be successfully and reliably surface mounted.

Figure on page3 shows a sample temperature profile compliant to JEDEC standards. You can use this example as a generic target to set up your reflow process. You should adhere to the JEDEC profile limits as well as specifications and recommendations from the solder paste manufacturer to avoid damaging the device and create a reliable solder joint.

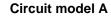


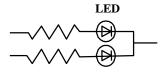


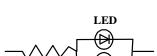
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#### 7.5 Drive Method

A LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.







**Circuit model B** 

- (A) Recommended circuit.
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

#### 7.6 ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents.

To verify for ESD damage, check for "lightup " and Vf of the suspect LEDs at low currents.

The Vf of " good " LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AlInGaP product.





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### 8. Reliability Test

Classification	Test Item	Test Condition	Reference Standard
	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
Endurance	High Temperature High Humidity Storage	Ta= 65±5⁰C,RH= 90∼95% *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-202F:103B JIS C 7021:B-11
Test	High Temperature Storage	Ta= 105±5 ºC *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-883D:1008 JIS C 7021:B-10
	Low Temperature Storage	Ta= -55±5 ℃ *Test Time= 1000HRS (-24HRS,+72H RS)	JIS C 7021:B-12
	Temperature Cycling	$105 ^{\circ}\text{C} \sim 25 ^{\circ}\text{C} \sim -55 ^{\circ}\text{C} \sim 25 ^{\circ}\text{C}$ 30mins 5mins 30mins 5mins 10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS C 7021:A-4
	Thermal Shock	85 ± 5 °C ~ -40 °C ± 5 °C 10mins 10mins 10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
Environmental	Solder Resistance	T.sol= 260 ± 5 °C Dwell Time= 10 ± 1secs	MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
Test	IR-Reflow	Ramp-up rate(217 °C to Peak) +3 °C / second max Temp. maintain at 175(±25) °C 180 seconds max Temp. maintain above 217 °C 60-150 seconds Peak temperature range 260 °C +0/-5 °C Time within 5°C of actual Peak Temperature (tp) 10-30 seconds Ramp-down rate +6 °C /second max	MIL-STD-750D:2031.2 J-STD-020D
	Solder ability	T.sol= $235 \pm 5 ^{\circ}$ C Immersion time $2\pm 0.5 $ sec Immersion rate $25\pm 2.5 $ mm/sec Coverage $\geq 95\%$ of the dipped surface	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2

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Part No. : LTST-A07RGB BNS-OD-FC002/A4

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### 9. Others

The appearance and specifications of the product may be modified for improvement without prior notice.

### **10. Suggested Checking List**

Training and Certification

- 1. Everyone working in a static-safe area is ESD-certified?
- 2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

- 1. Static-safe workstation or work-areas have ESD signs?
- 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
- 3. All ionizer activated, positioned towards the units?
- 4. Each work surface mats grounding is good?

#### Personnel Grounding

- 1. Every person (including visitors) handling ESD sensitive (ESDS) items wears wrist strap, heel strap or conductive shoes with conductive flooring?
- 2. If conductive footwear used, conductive flooring also present where operator stand or walk?
- 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V\*?
- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- 5. All wrist strap or heel strap checkers calibration up to date?

Note: \*50V for InGaN LED.

#### **Device Handling**

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycles?

#### Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?



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